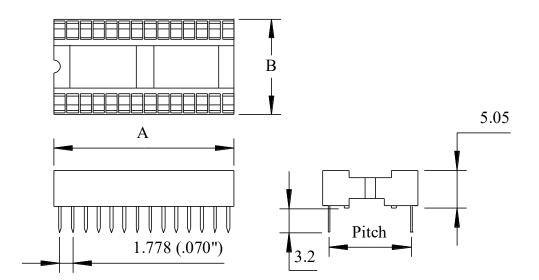


Data Sheet – Shrink Stamped I.C. Sockets W3100/xxxTRC W3100/xxxT

The W3100 Shrink Series uses a phosphor bronze contact with 2 plating options RHoS compliant Tin or Tin/Lead . Moulding material is 30%GF PBT rated to UL 94 V-0. Designed for automatic PCB loading machines features include; overstress protection, large target area for ease of IC insertion and a 35 degree angled contact to prevent the IC leg from going behind the contact during insertion.





Part No	Pins	Pitch	А	В	Part No	Pins	Pitch	А	В
W3124/407TRC	24	10.16	21.34	12.70	W3124/407T	24	10.16	21.34	12.70
W3128/407TRC	28	10.16	24.89	12.70	W3128/407T	28	10.16	24.89	12.70
W3130/407TRC	30	10.16	26.67	12.70	W3130/407T	30	10.16	26.67	12.70
W3140/607TRC	40	15.24	35.56	17.78	W3140/607T	40	15.24	35.56	17.78
W3142/607TRC	42	15.24	37.33	17.78	W3142/607T	42	15.24	37.33	17.78
W3164/607TRC	64	19.05	56.89	21.59	W3164/607T	64	19.05	56.89	21.59



Data Sheet – Shrink Stamped I.C. Sockets W3100/xxxTRC W3100/xxxT

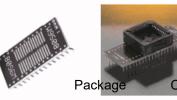
General Specifications. Unless stated all values are typical.

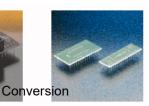
<u>Contact</u> Resistance: Current Rating: Capacitance:	10m ohms 10 amp cont. 2.0 amp peak. 0.5pF					
Material:	Phosphor Bronze					
Plating:	W3100TRC Nickel 2.5 microns over Pure Tin 6.0 microns W3100T 60/40 tin/lead 2/3 microns. W3100G Gold in contact area only with solder tail microns over plated Nickel 2.5 Pure Tin 6.0 microns					
Insertion Force: Withdrawal Force: Point of contact:	120/130 grams (1.18/1.27n) per pin 0.01" diameter. 50/70 grams (0.49/0.69n) per pin 0.01" diameter. 0.061" (1.70mm) from top of socket.					
Force to remove From moulding:	1.0lb minimum					
Moulding						
Material:	Glass-reinforced Polyester (PBT)					
Insulation Resistance:	1010 Ohms (contact to contact) at 500VDC					
Arc Resistance:	145 seconds at 23 degrees C					
Electrical Strength:	121KV/cm at 23 degrees C					
Dielectric Constant:	3.9 (48 hrs 90%RH) at 100Hz 23 degrees C					
	4.5 at 100Hz 121 degrees C					
	3.7 (48 hrs 90%RH) at 1MHz 23 degrees C					
Dissipation Factor:	4.3 at 1MHz 121 degrees C 0.0077 (48 hrs 30%RH) at 100Hz 23 degrees C					
Dissipation Factor.	0.0300 at 100Hz 121 degrees C					
	0.0150 (48 hrs 30%RH) at 1MHz 23 degrees C					
	0.0200 at 1MHz 121 degrees C					
Volume Resistively:	3 x 1013ohms-CM (48 hrs 90%RH) at 25 degrees C 1013ohms-CM at 121 degrees C					
Operating Temperature: Flammability:	-65 to 150 degrees C UL94V-0					

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Pitch Change

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